



Final Product Change Notification

202407031F01 : PCA9956BTW Wire Conversion from Gold to Copper

Note: This notice is NXP Company Proprietary.

Issue Date: Aug 05, 2024 **Effective Date:** Nov 08, 2024

Here is your personalized communication about an NXP notification.
For detailed information we invite you to [view this notification online](#)

Management summary

NXP will change the wire for the bonding process of the PCA9956BTW product, from gold to copper for improved reliability and manufacturing logistics. This will align the manufacturing process and flow of this product to industry standard.

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware <input type="checkbox"/> Other | | | | |

Notification Overview

Description

ATBK will convert to copper wire for this product.

Reason

Copper wire will improve overall product reliability and reduce logistics risks in production, by moving the product, to standard, current production materials.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Sep 30, 2024

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Sep 04, 2024.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Beiping Zhang
Position Quality Engineer
e-mail address beiping.zhang_1@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2024 NXP Semiconductors. All rights reserved.